



REVISION RECORD			
LN	REV NO	APPROVED	DATE

- Notes:**
- Top & Bottom metallization Immersion Gold.
  - Metallization 0.5 oz copper.
  - Plate Vias with 1 oz copper.
  - "YELLOW" soldermask top and bottom.
  - Top & bottom silkscreen "BLACK". Bottom mirrored.
  - Do not cut copper back from edge of board.
  - Ship individual pieces.
  - Maintain .093 board thickness.
  - Warp and twist shall not exceed .007 per inch.
  - Copper overlap to board edge intentional.
  - Dielectric thickness between layers 6 and 7 may be used to adjust total board thickness to particular thickness.
  - Fill 8mil Via with non-conductive epoxy.
  - Soldermask web must be present through all QFN's .

**CONFIDENTIALITY NOTICE:**  
 Any review, retransmission, dissemination, or use of this information by persons or entities other than the intended recipients is strictly prohibited.

**12 Layers**

	.008 Rogers 4003
	.0062 FR408
	.008 FR408
	.0062 FR408
	.008 FR408
	~.0105 FR408
	.008 FR408
	.0062 FR408
	.008 FR408
	.0062 FR408
	.008 Rogers 4003

↑ .093 +/- .10% ↓

DESIGNER: Jason Thom		DATE: 03-24-09		TITLE: Master's Thesis Measurement Board	
CHECKED:	DATE:	CODE:	REV:	SIZE: A2	DRAWING NO: P342
QUALITY CONTROL:	DATE:	SCALE:	SHEET:	1 of 1	
RELEASED:	DATE:				